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October 1996 Revised June 2005

74VCX16244

Low Voltage 16-Bit Buffer/Line Driver with 3.6V Tolerant Inputs and Outputs

General Description

The VCX16244 contains sixteen non-inverting buffers with 3-STATE outputs to be employed as a memory and address driver, clock driver, or bus oriented transmitter/receiver. The device is nibble (4-bit) controlled. Each nibble has separate 3-STATE control inputs which can be shorted together for full 16-bit operation.

The 74VCX16244 is designed for low voltage (1.2V to 3.6V) $\rm V_{CC}$ applications with I/O capability up to 3.6V.

The 74VCX16244 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining low CMOS power dissipation.

Features

- 1.2V to 3.6V V_{CC} supply operation
- 3.6V tolerant inputs and outputs
- ton

2.5 ns max for 3.0V to 3.6V V_{CC}

- Power-off high impedance inputs and outputs
- Supports live insertion and withdrawal (Note 1)
- \blacksquare Static Drive (I_OH/I_OL)

±24 mA @ 3.0V V_{CC}

- Uses proprietary noise/EMI reduction circuitry
- Latch-up performance exceeds 300 mA
- ESD performance:

 $Human\ body\ model > 2000V$

Machine model > 200V

Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA)

Note 1: To ensure the high-impedance state during power up or power down, $\overline{\text{DE}}$ should be tied to V_{CC} through a pull-up resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

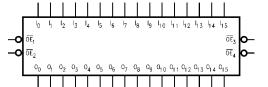
Ordering Code:

Order Number	Package Number	Package Description
74VCX16244G (Note 2)(Note 3)	BGA54A	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide
74VCX16244MTD (Note 3)	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Note 2: Ordering Code "G" indicates Tray.

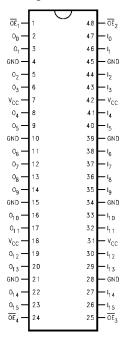
Note 3: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol

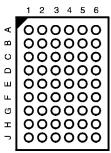


Connection Diagrams

Pin Assignment for TSSOP



Pin Assignment for FBGA



(Top Thru View)

Pin Descriptions

Pin Names	Description			
OE _n	Output Enable Input (Active LOW)			
I ₀ -I ₁₅	Inputs			
I ₀ -I ₁₅ O ₀ -O ₁₅	Outputs			
NC	No Connect			

FBGA Pin Assignments

	1	2	3	4	5	6
Α	O ₀	NC	OE ₁	OE ₂	NC	I_0
В	O ₂	O ₁	NC	NC	I ₁	l ₂
С	O ₄	O ₃	V _{CC}	V _{CC}	l ₃	I ₄
D	O ₆	O ₅	GND	GND	I ₅	I ₆
Е	O ₈	07	GND	GND	I ₇	I ₈
F	O ₁₀	O ₉	GND	GND	l ₉	I ₁₀
G	O ₁₂	O ₁₁	V _{CC}	V _{CC}	I ₁₁	I ₁₂
Н	O ₁₄	O ₁₃	NC	NC	I ₁₃	I ₁₄
J	O ₁₅	NC	OE ₄	ŌE ₃	NC	I ₁₅

Truth Tables

Inputs		Outputs
OE ₁	I ₀ -I ₃	O ₀ -O ₃
L	L	L
L	Н	Н
Н	X	Z

Inp	outs	Outputs
ŌE ₃	I ₈ -I ₁₁	O ₈ -O ₁₁
L	L	L
L	Н	Н
Н	X	Z

Inputs		Outputs
OE ₂	I ₄ -I ₇	O ₄ -O ₇
L	L	L
L	Н	Н
Н	Χ	Z

Inj	outs	Outputs
ŌE₄	I ₁₂ -I ₁₅	O ₁₂ -O ₁₅
L	L	L
L	Н	Н
н	X	Z

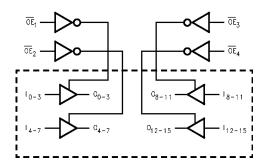
H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial (HIGH or LOW, inputs may not float)
Z = High Impedance

Functional Description

The 74VCX16244 contains sixteen non-inverting buffers with 3-STATE outputs. The device is nibble (4 bits) controlled with each nibble functioning identically, but independent of each other. The control pins may be shorted together to obtain full 16-bit operation. The 3-STATE out-

puts are controlled by an Output Enable (\overline{OE}_n) input. When \overline{OE}_n is LOW, the outputs are in the 2-state mode. When \overline{OE}_n is HIGH, the standard outputs are in the high impedance mode but this does not interfere with entering new data into the inputs.

Logic Diagram



Absolute Maximum Ratings(Note 4)

Supply Voltage (V_{CC}) -0.5V to +4.6V DC Input Voltage (V_I) -0.5V to +4.6V Output Voltage (V_O)

Outputs 3-STATED -0.5V to +4.6VOutputs Active (Note 5) -0.5V to V_{CC} +0.5V

DC Input Diode Current (I_{IK}) $V_I < 0V$ -50 mA

DC Output Diode Current (I_{OK})

 $V_{O} < 0V$ -50 mA $V_O > V_{CC}$ +50 mA

DC Output Source/Sink Current

 (I_{OH}/I_{OL}) $\pm 50 \text{ mA}$

DC V_{CC} or GND Current per

±100 mA Supply Pin (I_{CC} or GND) -65°C to +150°C

Storage Temperature Range (T_{STG})

Recommended Operating Conditions (Note 6)

Power Supply

1.2V to 3.6V Operating Input Voltage -0.3V to +3.6V

Output Voltage (V_O)

Output in Active States 0.0V to V_{CC} Output in 3-State 0.0V to 3.6V

Output Current in I_{OH}/I_{OL}

 $V_{CC} = 3.0V \text{ to } 3.6V$ ±24 mA

 $V_{CC} = 2.3V \text{ to } 2.7V$ ±18 mA $V_{CC} = 1.65V \text{ to } 2.3V$ ±6 mA $V_{CC} = 1.4V \text{ to } 1.6V$ ±2 mA

 $V_{CC} = 1.2V$ ±100 μA

-40°C to +85°C

Free Air Operating Temperature (T_A) Minimum Input Edge Rate ($\Delta t/\Delta V$)

 V_{IN} = 0.8V to 2.0V, V_{CC} = 3.0V 10 ns/V

Note 4: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical . Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 5: IO Absolute Maximum Rating must be observed.

Note 6: Floating or unused inputs must be held HIGH or LOW.

DC Electrical Characteristics

Symbol	Parameter	Conditions	V _{CC} (V)	Min	Max	Units
V _{IH}	HIGH Level Input Voltage		2.7 - 3.6	2.0		
			2.3 - 2.7	1.6		
			1.65 - 2.3	0.65 × V _{CC}		V
			1.4 - 1.6	0.65 × V _{CC}		
			1.2	0.65 x V _{CC}		
V _{IL}	LOW Level Input Voltage		2.7 - 3.6		0.8	
			2.3 - 2.7		0.7	
			1.65 - 2.3		$0.35 \times V_{CC}$	V
			1.4 - 1.6		$0.35 \times V_{CC}$	
			1.2		0.05 x V _{CC}	
V _{OH}	HIGH Level Output Voltage	I _{OH} = -100 μA	2.7 - 3.6	V _{CC} - 0.2		
		I _{OH} = −12 mA	2.7	2.2		
		I _{OH} = -18 mA	3.0	2.4		
		$I_{OH} = -24 \text{ mA}$	3.0	2.2		
		$I_{OH} = -100 \mu A$	2.3 - 2.7	V _{CC} - 0.2		
		$I_{OH} = -6 \text{ mA}$	2.3	2.0		
		I _{OH} = -12 mA	2.3	1.8		V
		I _{OH} = -18 mA	2.3	1.7		
		$I_{OH} = -100 \mu A$	1.65 - 2.3	V _{CC} - 0.2		
		$I_{OH} = -6 \text{ mA}$	1.65	1.25		
		I _{OH} = -100 μA	1.4 - 1.6	V _{CC} - 0.2		
		I _{OH} = -2 mA	1.4	1.05		
		$I_{OH} = -100 \mu A$	1.2	V _{CC} - 0.2		

DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC} (V)	Min	Max	Units
V _{OL}	LOW Level Output Voltage	I _{OL} = 100 μA	2.7 - 3.6		0.2	
		I _{OL} = 12 mA	2.7		0.4	
		I _{OL} = 18 mA	3.0		0.4	
		I _{OL} = 24 mA	3.0		0.55	
		$I_{OL} = 100 \mu A$	2.3 - 2.7		0.2	
		I _{OL} = 12 mA	2.3		0.4	V
		I _{OL} = 18 mA	2.3		0.6	V
		$I_{OL} = 100 \mu A$	1.65 - 2.3		0.2	
		I _{OL} = 6 mA	1.65		0.3	
		$I_{OL} = 100 \mu A$	1.4 - 1.6		0.2	
		I _{OL} = 2 mA	1.4		0.35	
		$I_{OL} = 100 \mu A$	1.2		0.05	
I	Input Leakage Current	$0 \leq V_I \leq 3.6V$	1.2 - 3.6		±5.0	μА
I _{OZ}	3-STATE Output Leakage	$0 \le V_O \le 3.6V$ $V_I = V_{IH} \text{ or } V_{IL}$	1.2 - 3.6		±10.0	μА
I _{OFF} I	Power-OFF Leakage Current	$0 \le (V_I, V_O) \le 3.6V$	0		10.0	μА
I _{CC}	Quiescent Supply Current	V _I = V _{CC} or GND	1.2 - 3.6		20.0	Δ.
		$V_{CC} \le (V_I, V_O) \le 3.6V \text{ (Note 7)}$	1.2 - 3.6		±20.0	μА
ΔI_{CC}	Increase in I _{CC} per Input	V _{IH} = V _{CC} -0.6V	2.7 - 3.6		750	μА

Note 7: Outputs disabled or 3-STATE only.

AC Electrical Characteristics (Note 8)

Symbol	Parameter	Conditions	V _{CC}	T _A = -40°	C to +85°C	Units	Figure
Cymbol	T di diffetei	Conditions	(V)	Min	Max		Number
t _{PHL}	Propagation Delay	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3	0.8	2.5		F:
t _{PLH}			2.5 ± 0.2	1.0	3.0		Figures 1, 2
			1.8 ± 0.15	1.5	6.0	ns	,
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1	1.0	12.0		Figures
			1.2	1.5	30.0		5, 6
t _{PZL}	Output Enable Time	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3	0.8	3.5		F:
t _{PZH}			2.5 ± 0.2	1.0	4.1		Figures 1, 3, 4
			1.8 ± 0.15	1.5	8.2	ns	, -,
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1	1.0	16.4		Figures
			1.2	1.5	41.0		5, 7, 8
t _{PLZ}	Output Disable Time	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3	0.8	3.5		F:
t _{PHZ}			2.5 ± 0.2	1.0	3.8		Figures 1, 3, 4
			1.8 ± 0.15	1.5	6.8	ns	
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1	1.0	13.6		Figures
			1.2	1.5	34.0		5, 7, 8
toshl	Output to Output Skew	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3		0.5		
toslh	(Note 9)		2.5 ± 0.2		0.5		
			1.8 ± 0.15		0.75	ns	
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1		1.5		
			1.2		1.5		

Note 8: For $C_L = 50_P F$, add approximately 300 ps to the AC maximum specification.

Note 9: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

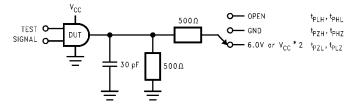
Dynamic Switching Characteristics

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = +25°C	Units
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	$C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0V$	1.8	0.25	
			2.5	0.6	V
			3.3	0.8	
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	$C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0V$	1.8	-0.25	
			2.5	-0.6	V
			3.3	-0.8	
V _{OHV}	Quiet Output Dynamic Valley V _{OH}	$C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0V$	1.8	1.5	
			2.5	1.9	V
İ			3.3	2.2	

Capacitance

Symbol	Parameter Conditions		$T_A = +25^{\circ}C$	Units
	r drameter	Conditions	Typical	Oilles
C _{IN}	Input Capacitance	$V_{CC} = 1.8, 2.5 \text{V or } 3.3 \text{V}, V_{I} = 0 \text{V or } V_{CC}$	6.0	pF
C _{OUT}	Output Capacitance	$V_{I} = 0V \text{ or } V_{CC}, V_{CC} = 1.8V, 2.5V \text{ or } 3.3V$	7.0	pF
C _{PD}	Power Dissipation Capacitance	$V_I = 0V \text{ or } V_{CC}, f = 10 \text{ MHz}, V_{CC} = 1.8V, 2.5V \text{ or } 3.3V$	20.0	pF

AC Loading and Waveforms (V $_{CC}$ 3.3V \pm 0.3V to 1.8V \pm 0.15V)



TEST	SWITCH
t_{PLH},t_{PHL}	Open
t_{PZL}, t_{PLZ}	6V at V $_{CC}$ = 3.3 \pm 0.3V; V $_{CC}$ x 2 at V $_{CC}$ = 2.5 \pm 0.2V; 1.8V \pm 0.15V
t _{PZH} , t _{PHZ}	GND

FIGURE 1. AC Test Circuit

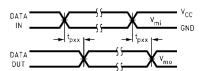


FIGURE 2. Waveform for Inverting and Non-Inverting Functions

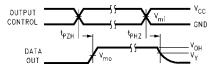


FIGURE 3. 3-STATE Output High Enable and Disable Times for Low Voltage Logic

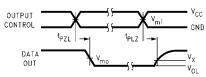
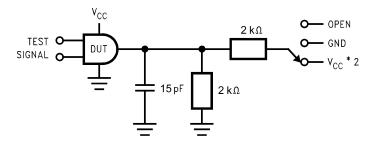


FIGURE 4. 3-STATE Output Low Enable and Disable Times for Low Voltage Logic

Symbol	V _{CC}		
Symbol	3.3V ± 0.3V	2.5V ± 0.2V	1.8V ± 0.15V
V _{mi}	1.5V	V _{CC} /2	V _{CC} /2
V _{mo}	1.5V	V _{CC} /2	V _{CC} /2
V _X	V _{OL} +0.3V	V _{OL} +0.15V	V _{OL} +0.15V
V _Y	V _{OH} -0.3V	V _{OH} -0.15V	V _{OH} -0.15V

AC Loading and Waveforms (V $_{CC}$ 1.5 \pm 0.1V to 1.2V)



t_{PZH}, t_{PHZ}

TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t_{PZL}, t_{PLZ}	V_{CC} x 2 at V_{CC} = 1.5 \pm 0.1V
t_{PZH}, t_{PHZ}	GND

FIGURE 5. AC Test Circuit

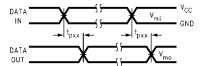


FIGURE 6. Waveform for Inverting and Non-Inverting Functions

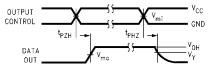


FIGURE 7. 3-STATE Output High Enable and Disable Times for Low Voltage Logic

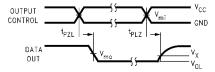
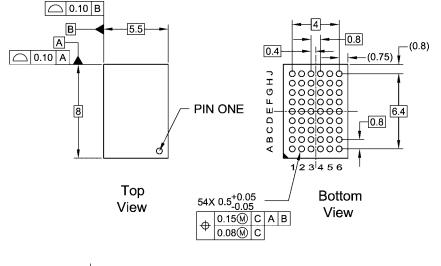
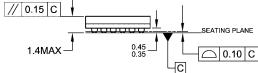


FIGURE 8. 3-STATE Output Low Enable and Disable Times for Low Voltage Logic

Symbol	V _{CC}	
Cymbol .	1.5V ± 0.1V	
V _{mi}	V _{CC} /2	
V _{mo}	V _{CC} /2	
V _X	V _{OL} + 0.1V	
V_{Y}	V _{OH} – 0.1V	

Physical Dimensions inches (millimeters) unless otherwise noted





NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- **B. ALL DIMENSIONS IN MILLIMETERS**
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
 .35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
 D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA54ArevD

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide Package Number BGA54A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 12.50±0.10 0.40 TYP -B-99. 9.20 8.10 50. O.2 C B A ALL LEAD TIPS PIN #1 IDENT 0.50 LAND PATTERN RECOMMENDATION 0.1 C SEE DETAIL A 0.90+0.15 ALL LEAD TIPS 0.09-0.20 0.10±0.05 0.17-0.27 0.50 ♦ 0.13\@ A B\S C\S 12.00' TOP & BOTTOM DIMENSIONS ARE IN MILLIMETERS R0.16 GAGE PLANE 0.25 NOTES: A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ED, DATE 4/97. B. DIMENSIONS ARE IN MILLIMETERS. SEATING PLANE 0.60±0.10 1.00 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. DETAIL A MTD48REVC

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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